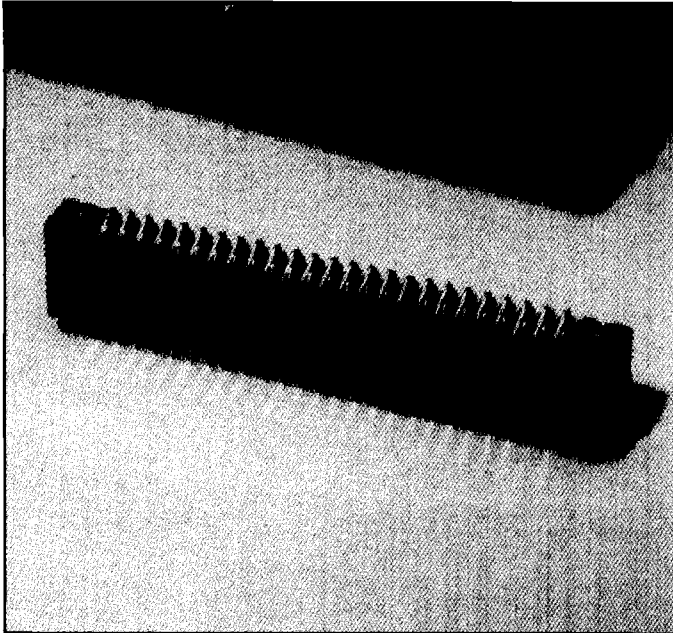


Series 501 & 503 (Dip Solder)

.050 (1.27) Centers
Surface Mate
Surface Compression



PART NUMBER CODING 50X-X 1-XX DS(X)-00-XX

CONTACT PLATING
CONTACT SURFACE **TERMINATION**
23 = .000030 GOLD TIN/LEAD
25 = .000050 GOLD TIN/LEAD
41 = TIN PLATING
ALL GOLD AND TIN OVER .000050
NICKEL
FOR OTHER PLATING CONSULT
FACTORY

STD. MOUNTING STYLE/HARDWARE
SEE MOUNTING STYLE TABLE

TERMINATION STYLE
DS1 = DIP SOLDER (.100 LONG)
DS2 = DIP SOLDER (.125 LONG)

NUMBER OF CONTACTS
SINGLE ROW .100 (2.54) CENTERS
15 (CONSULT FACTORY FOR
AVAILABILITY)
21 STANDARD
25 STANDARD

DUAL ROW .050 (1.27) CENTERS
30 (CONSULT FACTORY FOR
AVAILABILITY)
42 STANDARD
50 STANDARD

INSULATOR MATERIAL
1 = POLYESTER, BLACK

NUMBER OF ROWS
1 = 1 ROW
2 = 2 ROWS

SURFACE MATE (DIP SOLDER)
501 = .325 HIGH INSULATORS
503 = .538 HIGH INSULATORS
(CONSULT FACTORY FOR
AVAILABILITY OF ADDITIONAL
INSULATOR HEIGHTS)

Features

- Combines board standoff function with parallel board interconnection function
- Dip solder tails allow conventional flow soldering
- Separable screw down connection of daughter boards
- Optional polarizing mounting hardware (threaded and thru-hole)
- Connects thru-hole and surface mount boards
- Various contact platings are available

Specifications

Operating Voltage: 250 VDC RMS at 60 Hz at sea level

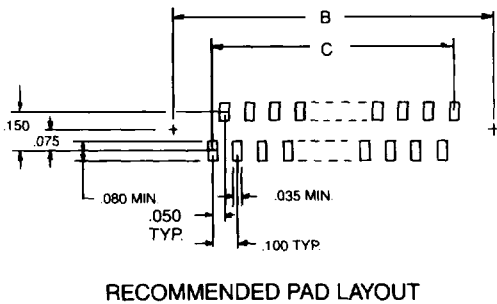
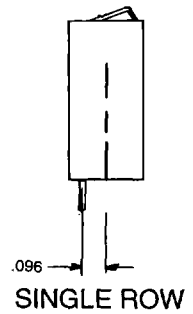
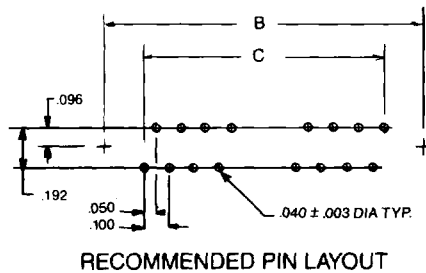
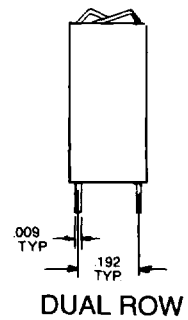
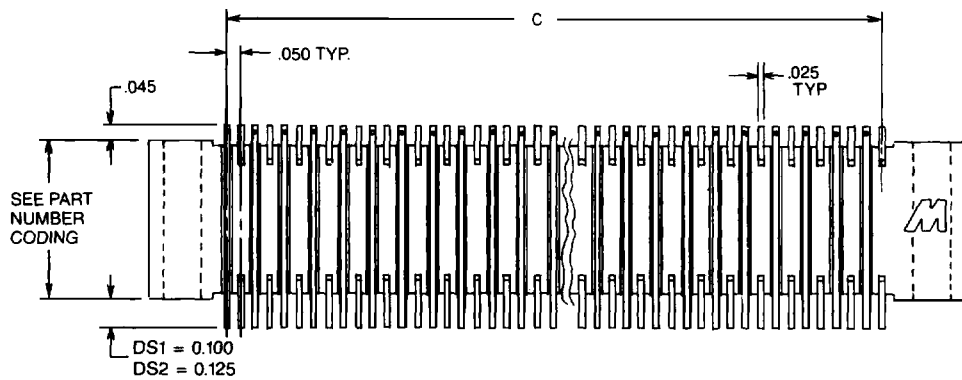
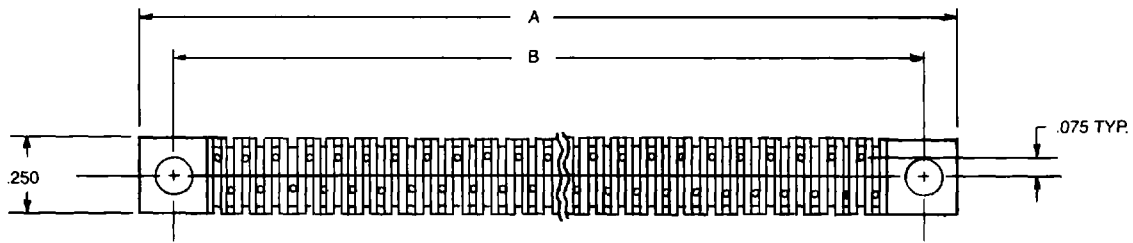
Current Rating: 2.0 amps continuous

Contact Resistance: 25 milliohms maximum

Contact Material: Copper alloy

Contact Plating: See part number coding

Insulator Material: Polyester, glass filled 94 V-0 rated per MIL-M-24519, black



50	3.000	2.750	2.450
42	2.600	2.350	2.050
30	2.000	1.750	1.450
SIZE	A	B	C
DIMENSIONS			